



PATENT

Case Docket No. ASMMC.033AUS

Date: April 28, 2003

Page 1

In re application of : Kim et al.  
App. No. : 10/007,304  
Filed : December 5, 2001  
For : COPPER INTERCONNECT  
STRUCTURE HAVING  
STUFFED DIFFUSION  
BARRIER  
Examiner : RAO  
Art Unit : 2814

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April 28, 2003

(Date)

Andrew N. Merickel, Reg. No. 53,317

UNITED STATES PATENT AND TRADEMARK OFFICE  
P.O. Box 2327  
Arlington, VA 22202

Sir:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated as shown below:

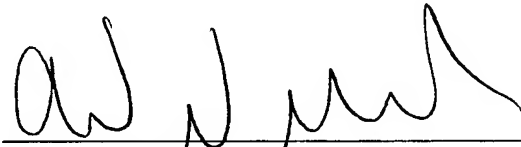
CLAIMS AS FILED						
	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
Total Claims	58	—	58	= 0 ×	\$18	= \$0
Independent Claims	7	—	7	= 0 ×	\$84	= \$0
If application has been amended to contain multiple dependent claim(s), then add					\$280	= \$0
Time Extension Fee						\$0
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$0

(X) Response to Office Action in 5 pages.

(X) Return prepaid postcard.

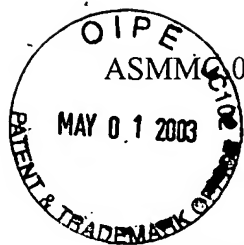
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Andrew N. Merickel  
Registration No. 53,317  
Attorney of Record  
Customer No. 20,995  
(415) 954-4114



#11/Response  
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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Kim et al.  
Appl. No. : 10/007,304  
Filed : December 5, 2001  
For : COPPER INTERCONNECT  
STRUCTURE HAVING  
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Group Art Unit 2814

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April 28, 2003

(Date)

Andrew N. Menckel, Reg. No. 53,317

Response to Office Action

United States Patent and Trademark Office  
P.O. Box 2327  
Arlington, VA 22202

Dear Sir:

The present paper is submitted in response to the Office Action mailed on January 30, 2003. Applicants respectfully request reconsideration of the rejections in view of the remarks below.

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